

AMENDMENTS TO THE CLAIMS

Cancel claims 1 and 8-28 without prejudice.

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (canceled)

2. (currently amended) ~~The apparatus of claim 1, further comprising:~~

An apparatus comprising:

a substrate;

a pair of signal traces formed directly on the substrate and spaced from each other;

a filler material on the substrate and between the signal traces, the filler material having a dielectric constant that is higher than a dielectric constant of a material of which the substrate is formed; and

a solder mask layer on the signal traces and on the filler material, the dielectric constant of the filler material being higher than a dielectric constant of the solder mask layer.

3. (currently amended) The apparatus of claim ~~1~~ 2, wherein the substrate includes a resin in which fibers are embedded, the dielectric constant of the filler material being higher than a dielectric constant of the resin.

4. (currently amended) The apparatus of claim ~~1~~ 2, wherein the signal traces are formed of copper.

5. (currently amended) The apparatus of claim + 2, wherein the filler material substantially fills a space between the signal traces.

6. (currently amended) The apparatus of claim + 2, wherein the filler material has a height that is substantially equal to a height of the signal traces.

7. (currently amended) The apparatus of claim + 2, wherein the filler material has a dielectric constant in excess of 4.

8-28 (canceled)

29. (new) The apparatus of claim 2, wherein the filler material includes polyvinylidene difluoride.